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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Lee

Attorney Docket No.: NOVLP033X1
/NVLS-000498X1

Application No.: 10/649,351

Examiner: NGUYEN, HA

Filed: August 26, 2003

Group: 2812

Title: METHOD FOR PRODUCING ULTRA-
THIN TUNGSTEN LAYERS WITH
IMPROVED STEP COVERAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on December 5, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Tara Hayden

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP033X1).

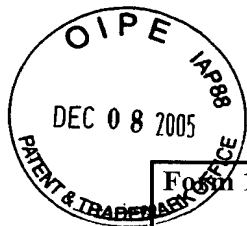
Respectfully submitted,

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Form 1449 (Modified)	Atty Docket No. NOVLP033X1/NVLS-000498X1	Application No.: 10/649,351
Information Disclosure Statement By Applicant	Applicant: Lee et al.	
(Use Several Sheets if Necessary)	Filing Date August 26, 2003	Group 1762

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	2002/0177316	11.2002	Miller et al.			
	A2	6,962,873	11.2005	Park, Heung L.			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	U.S. Office Action mailed November 8, 2004, from U.S. Application No. 10/984,126 [Atty Dkt. NOVLP058D1/NVLS-000732D1].
	C2	Chan et al., "Methods for Growing Low-Resistivity Tungsten Film", Novellus Systems, Inc., filed November 1, 2005, Application No. 11/265,531, pages 1-35. [NOVLP137/NVLS-0003093]
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.